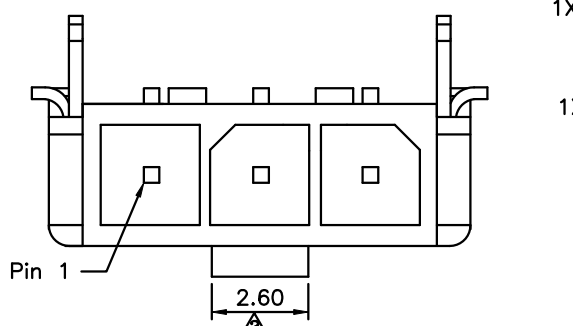
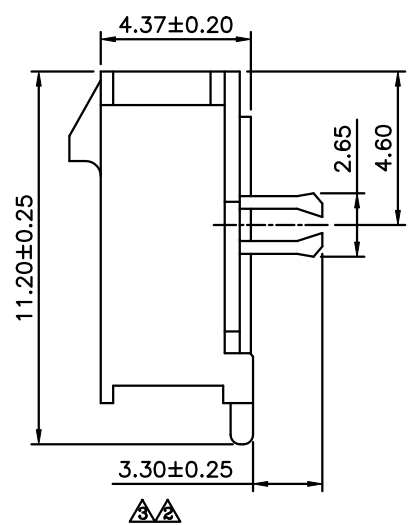
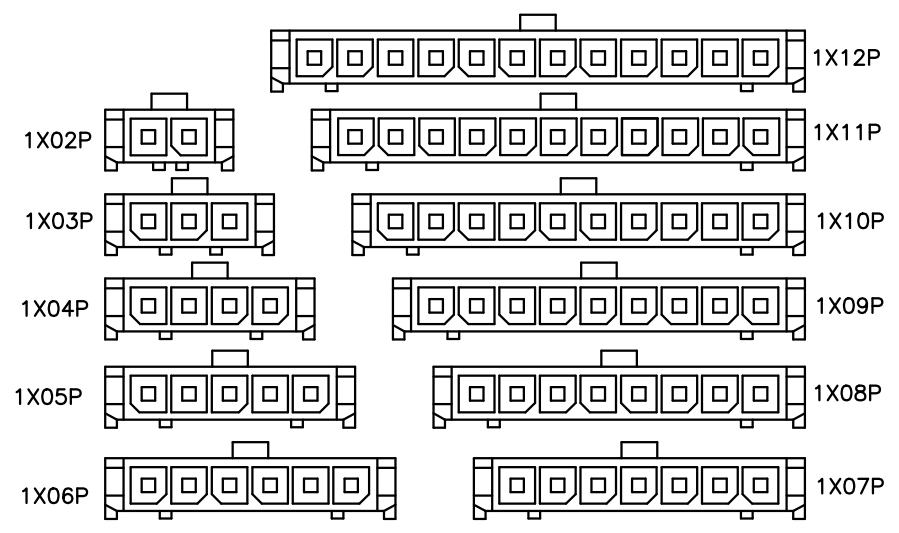
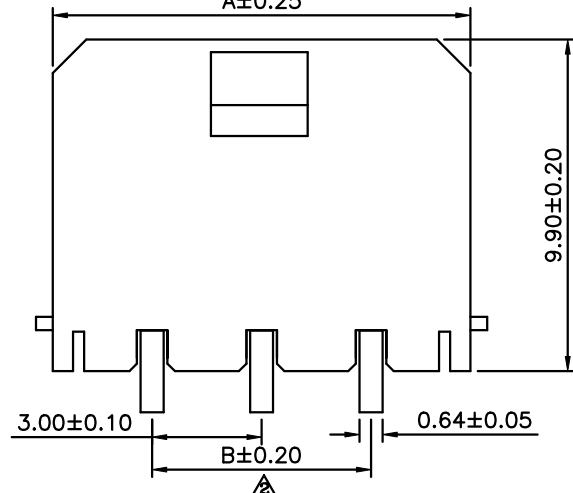


Recommended P.C.B. Layout



A±0.25



**SPECIFICATION**  
**1.General Characteristics**  
 3.0mm Micro-Fit Wafer 1XXX SMT 90°  
 With DIP Boardlock Black Insulator  
 Tin Plated Tape & Reel 250 PCS/Reel  
**2.Material&Finish**  
 Insulator:LCP(UL94V-0),Black  
 Contact:Brass,Tin Plated  
 Solder Tabs:Brass,Tin Plated  
**3.Electrical Characteristics**  
 Current Rating:5A AC,DC  
 Voltage Rating:250V AC,DC  
 Withstanding Voltage:1500V AC/Minute  
 Insulation Resistance:1000 Megaohms Min.  
 Contact Resistance:20 Milliohms Max.  
**4.Environmental Characteristics**  
 Temperature Range:-25°C~+85°C  
**5.RoHS Compliant**

MIF 1 X XX P WZ - R2H5 - H  
 (1) (2) (3) (4) (5) (6) (7)

- (1) MIF:3.0mm Micro-Fit Series
- (2) 1:Single Row
- (3) XX:No. Of Position/Per Row
- (4) P:Male
- (5) WZ:SMT Right Angle With Boardlock
- (6) R2H5:Tape & Reel 250 PCS/Reel
- (7) H:RoHS Compliant

Pin	A	B	C
02	9.65	3.00	7.30
03	12.65	6.00	10.30
04	15.65	9.00	13.30
05	18.65	12.00	16.30
06	21.65	15.00	19.30
07	24.65	18.00	22.30
08	27.65	21.00	25.30
09	30.65	24.00	28.30
10	33.65	27.00	31.30
11	36.65	30.00	34.30
12	39.65	33.00	37.30

**AUK** A MEMBER OF AUK GROUP  
**太聯事業股份有限公司**  
**AUK CONTRACTORS CO., LTD.**

CATEGORY		APPROVED BY		UNLESS OTHERWISE SPECIFIED TOLERANCES ARE X ±0.30 △ ±0.25 XX ±0.20 XXX ±0.05 ANG. ±1°
PART No. △ MIF1XXXPWZ-R2H5-H		MEI		
DRAWING No. MIF1XXXPWZ-R2H5-H		CHECKED BY HZF		
SCALE NONE		DRAWING BY CYP		
REV.	A3	UNIT mm	NO. REV.	REVISIONS

△ A3	Modify Data	HZF	07/18/2016
△ A2	Modify Data	HZF	03/23/2016
△ A1	Modify P/N: MIF1XXXPWZ-H --> MIF1XXXPWZ-R2H5-H	HZF	12/08/2014
△ A0	NEW RELEASE	HZF	08/02/2012
NO. REV.	REVISIONS	CHK	DATE